

[Insert title of invention]SOLDER BALL COLLAPSE CONTROL APPARATUS AND METHOD THEREOF

Abstract of Disclosure

A solder ball collapse control apparatus and method thereof includes a plurality of first solder members, pieces of solder material in a shape capable of being used to properly create a solder joint. The first solder members have a first solder dimension and a first melting temperature and are disposed on a carrier substrate, wherein the first solder members include any piece of material capable of being disposed using a solder dispensing machine. The apparatus and method further includes a plurality of second members having a second dimension and a second melting temperature, disposed on the carrier substrate in relation to the plurality of first solder members. The second members include any piece of material capable of being disposed using the solder dispensing machine, wherein the first solder member dimension is greater than the second member dimension and the second melting temperature is greater than the first melting temperature.

Figures